Preface

The 8th International Conference on Manufacturing Science and Technology (ICMST 2017) was a comprehensive conference which focuses on manufacturing science and technology. ICMST 2017 was held in Think Tank, School of Design, Hong Kong Polytechnic University, Hong Kong during June 23-25, 2017. The main theme of the conference is to address and deliberate on the latest technical status and recent trends in the research and applications of manufacturing science and technology.

The purpose of the conference was to provide an opportunity for the scientists, engineers, industrialists, scholars and other professionals from all over the world to interact and exchange their new ideas and research outcomes in related fields and develop possible chances for future collaboration. The conference was also aimed at motivating the next generation of researchers to promote their interests in manufacturing science and technology.

The program of the conference included invited speeches and oral presentations in sessions, including poster presentations. The invited talks were focused on the potential application of manufacturing science and technology in various fields of application.

The proceedings contain 21 papers which have been selected from the conference with a total submission of 45 papers. Each contributed paper was rigorously peer-reviewed by two reviewers who were drawn from a large pool of technical committee members as well as other international reviewers in the related fields.

In the proceeding, readers can learn the most cutting-edge knowledge about manufacturing science and technology of researchers from all around the world.

On behalf of the organizing committee, we’d like to express our heartfelt gratitude to all the reviewers for their great professionalism and efforts. And thank all the participants and sponsors for their valuable contributions and support to ICMST 2017.

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Curtin University, Sarawak, Malaysia
June, 2017
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